

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	BSC019N02KS G	**Issued**	02. June 2021
MA#	MA001703076		
Package	PG-TDSON-8-39	**Weight***	114.74 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	5.248	4.57	4.57	45735	45735
leadframe	inorganic material	phosphorus	7723-14-0	0.015	0.01		127	
	non noble metal	iron	7439-89-6	0.049	0.04		425	
	non noble metal	copper	7440-50-8	48.649	42.41	42.46	423985	424537
wire	non noble metal	copper	7440-50-8	0.024	0.02	0.02	205	205
encapsulation	organic material	carbon black	1333-86-4	0.076	0.07		663	
	plastics	epoxy resin	-	6.011	5.24		52391	
	inorganic material	silicondioxide	60676-86-0	31.960	27.85	33.16	278533	331587
leadfinish	non noble metal	tin	7440-31-5	1.520	1.32	1.32	13247	13247
plating	noble metal	silver	7440-22-4	0.158	0.14	0.14	1381	1381
solder	non noble metal	tin	7440-31-5	0.079	0.07		689	
	noble metal	silver	7440-22-4	0.099	0.09		861	
	non noble metal	lead	7439-92-1	3.773	3.29	3.45	32885	34435
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.005			44	
	non noble metal	iron	7439-89-6	0.017	0.01		148	
	noble metal	silver	7440-22-4	0.150	0.13		1307	
	non noble metal	copper	7440-50-8	16.910	14.74	14.88	147374	148873
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 Neubiberg
Internet	www.infineon.com